

MOSFET - N-Channel, POWERTRENCH®

100 V, 164 A, 4.5 mΩ

FDP045N10A / FDI045N10A

Description

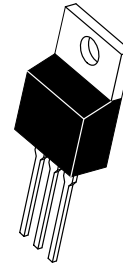
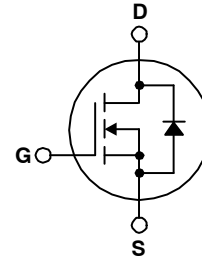
This N-Channel MOSFET is produced using onsemi's advance POWERTRENCH process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Features

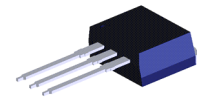
- $R_{DS(on)} = 3.8 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}$, $I_D = 100 \text{ A}$
- Fast Switching Speed
- Low Gate Charge, $Q_G = 54 \text{ nC}$ (Typ.)
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- High Power and Current Handling Capability
- This Device is Pb-Free and is RoHS Compliant

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter

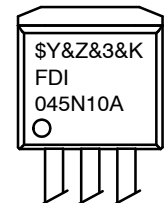
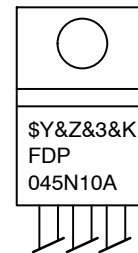


TO-220
CASE 221A-09



I²PAK
CASE 418AV

MARKING DIAGRAM



\$Y	= onsemi Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FDP/FDI045N10A	= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FDP045N10A / FDI045N10A

MOSFET MAXIMUM RATINGS (T_C = 25°C Unless Otherwise Noted)

Symbol	Parameter	FDP045N10A_F102 FDI045N10A_F102	Unit
V _{DSS}	Drain to Source Voltage	100	V
V _{GSS}	Gate to Source Voltage	±20	V
I _D	Drain Current	– Continuous (T _C = 25°C, Silicon Limited)	A
		– Continuous (T _C = 100°C, Silicon Limited)	
		– Continuous (T _C = 25°C, Package Limited)	
I _{DM}	Drain Current	– Pulsed (Note 1)	A
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	637	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	6.0	V/ns
P _D	Power Dissipation	(T _C = 25°C)	W
		– Derate Above 25°C	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	–55 to +175	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 120 A.

THERMAL CHARACTERISTICS

Symbol	Parameter	FDP045N10A_F102 FDI045N10A_F102	Unit
R _{θJC}	Thermal Resistance, Junction to Case, Max.	0.57	°C
R _{θJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDP045N10A_F102	FDP045N10A	TO-220	Tube	N/A	N/A	50 Units
FDI045N10A_F102	FDI045N10A	I ² -PAK	Tube	N/A	N/A	50 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 mA, V _{GS} = 0 V	100	–	–	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 mA, Referenced to 25°C	–	0.07	–	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V	–	–	1	μA
		V _{DS} = 80 V, T _C = 150°C	–	–	500	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	–	–	±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 250 mA	2.0	–	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 100 A	–	3.8	4.5	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 100 A	–	132	–	S

FDP045N10A / FDI045N10A

ELECTRICAL CHARACTERISTICS (T_C = 25°C Unless Otherwise Noted) (continued)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = 50 V, V _{GS} = 0 V f = 1 MHz	–	3960	5270	pF
C _{oss}	Output Capacitance		–	925	1230	pF
C _{rss}	Reverse Transfer Capacitance		–	34	–	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 50 V, V _{GS} = 0 V	–	1520	–	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{GS} = 10 V, V _{DS} = 50 V, I _D = 100 A (Note 4)	–	54	74	nC
Q _{gs}	Gate to Source Gate Charge		–	17	–	nC
Q _{gs2}	Gate Charge Threshold to Plateau		–	8	–	nC
Q _{gd}	Gate to Drain “Miller” Charge		–	13	–	nC
ESR	Equivalent Series Resistance (G–S)	f = 1 MHz	–	1.9	–	Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 100 A, V _{GS} = 10 V, R _G = 4.7 Ω (Note 4)	–	23	56	ns
t _r	Turn-On Rise Time		–	26	62	ns
t _{d(off)}	Turn-Off Delay Time		–	50	110	ns
t _f	Turn-Off Fall Time		–	15	40	ns

DRAIN-SOURCE DIODE CHARACTERISTICS

I _S	Maximum Continuous Drain to Source Diode Forward Current		–	–	164*	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		–	–	656	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 100 A	–	–	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, V _{DD} = 50 V, I _{SD} = 100 A, di/dt = 100 A/ms	–	75	–	ns
Q _{rr}	Reverse Recovery Charge		–	120	–	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. L = 3 mH, I_{AS} = 20.6 A, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 100 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C.
4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

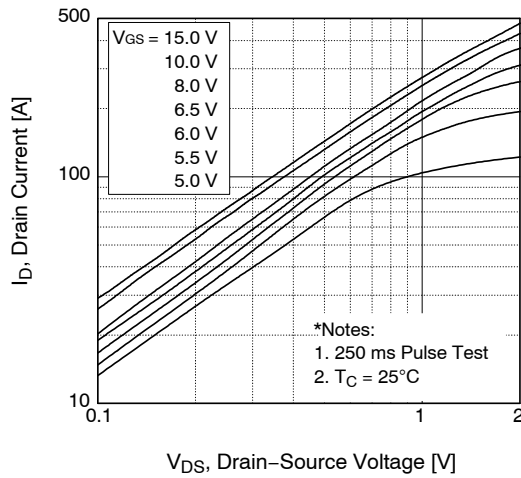


Figure 1. On-Region Characteristics

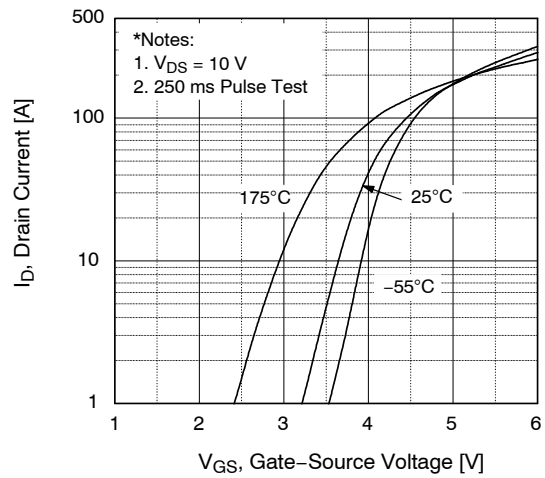


Figure 2. Transfer Characteristics

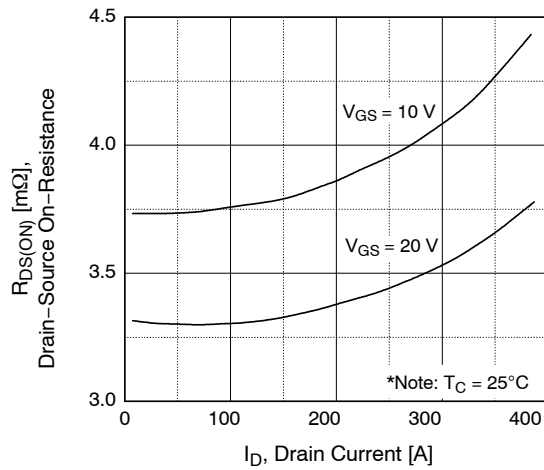


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

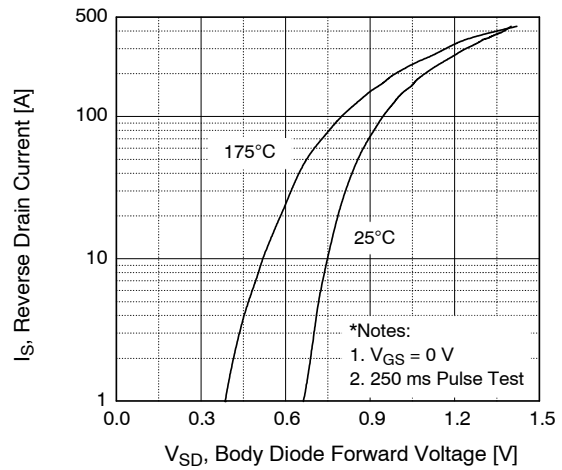


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

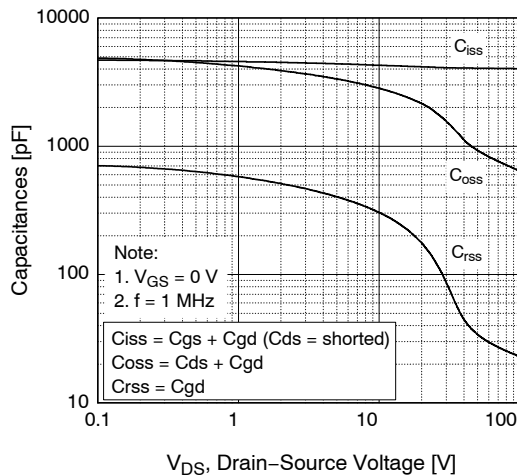


Figure 5. Capacitance Characteristics

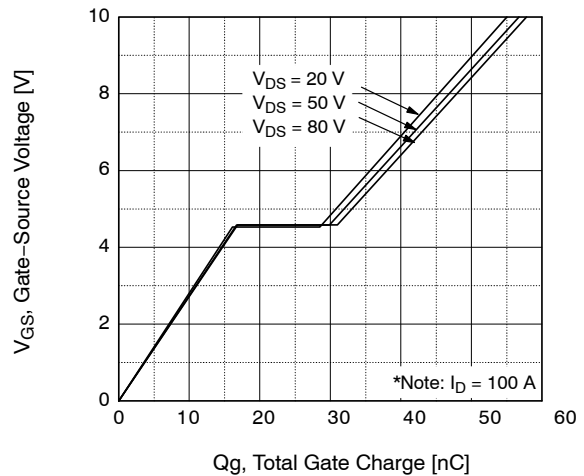


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

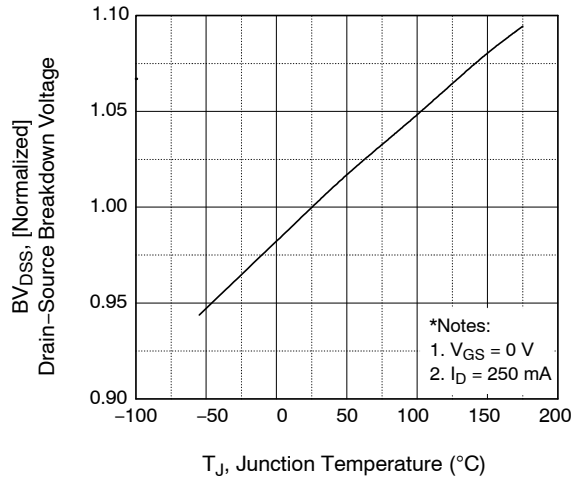


Figure 7. Maximum Safe Operating Area

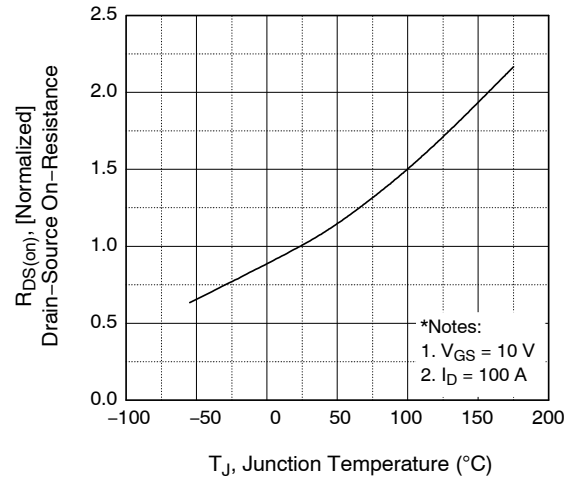


Figure 8. On-Resistance Variation vs. Temperature

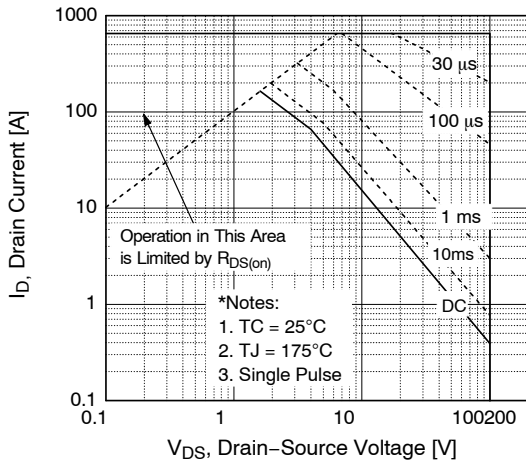


Figure 9. Maximum Safe Operating Area

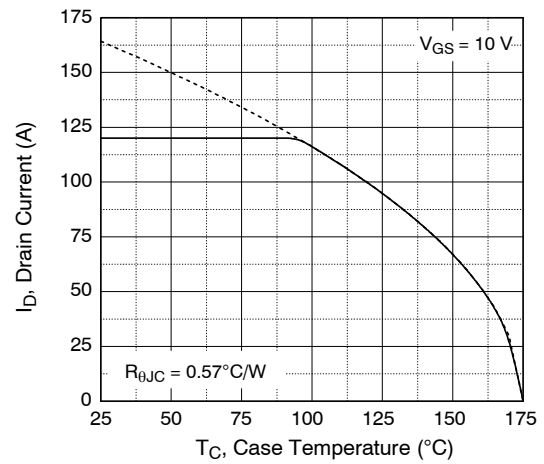


Figure 10. Maximum Drain Current vs. Case Temperature

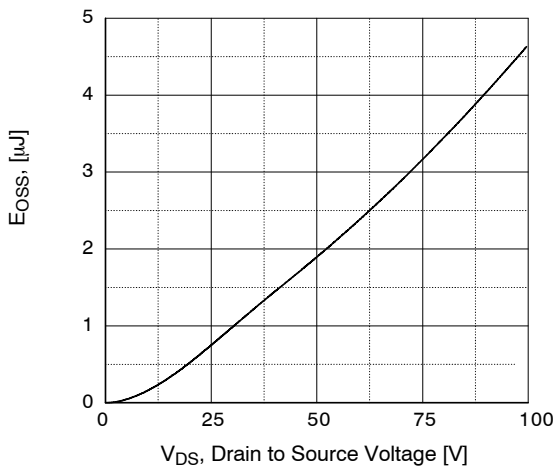


Figure 11. E_{oss} vs. Drain to Source Voltage

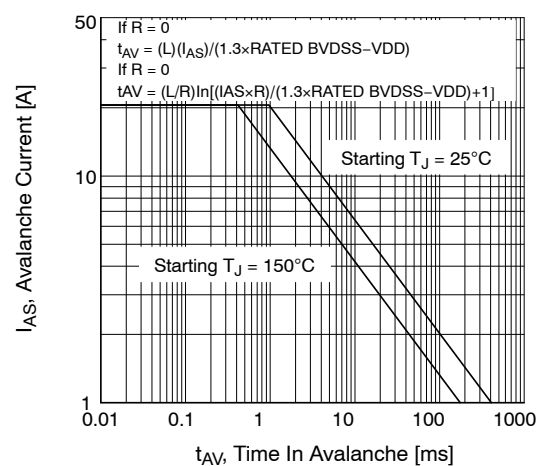


Figure 12. Unclamped Inductive Switching Capability

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

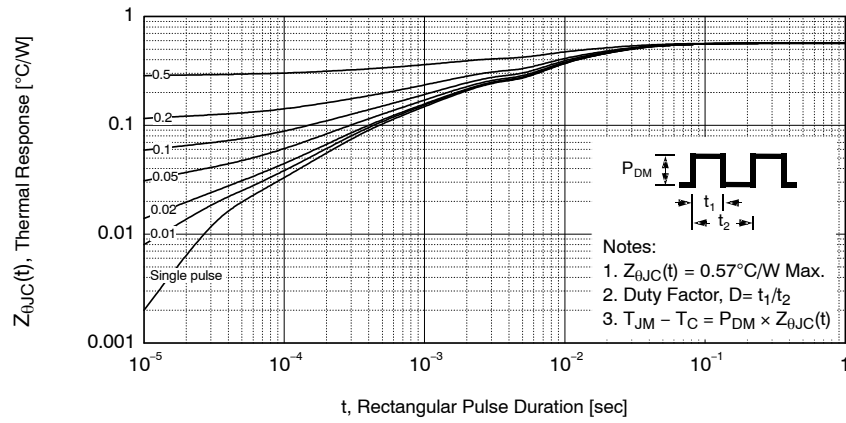


Figure 13. Transient Thermal Response Curve

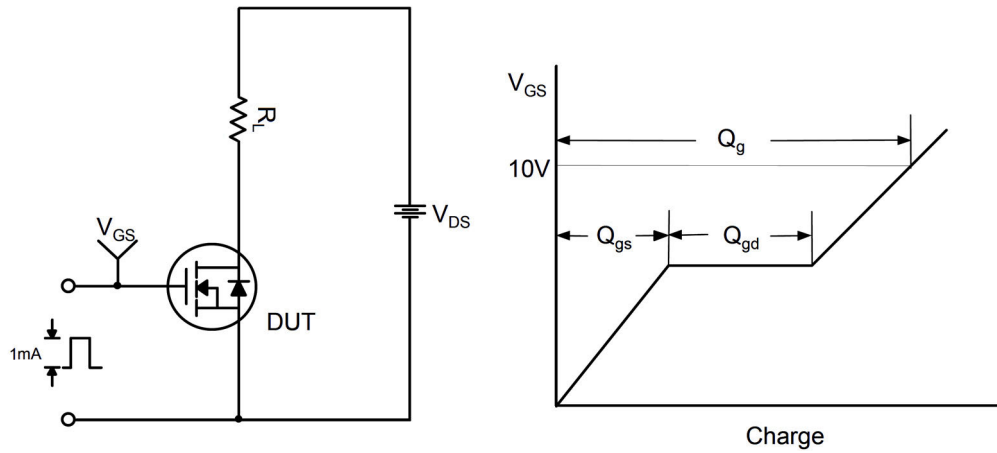


Figure 14. Gate Charge Test Circuit & Waveform

FDP045N10A / FDI045N10A

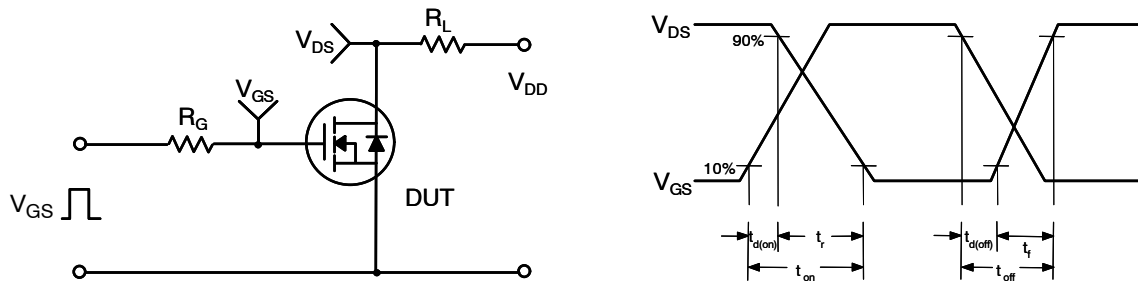


Figure 15. Resistive Switching Test Circuit & Waveforms

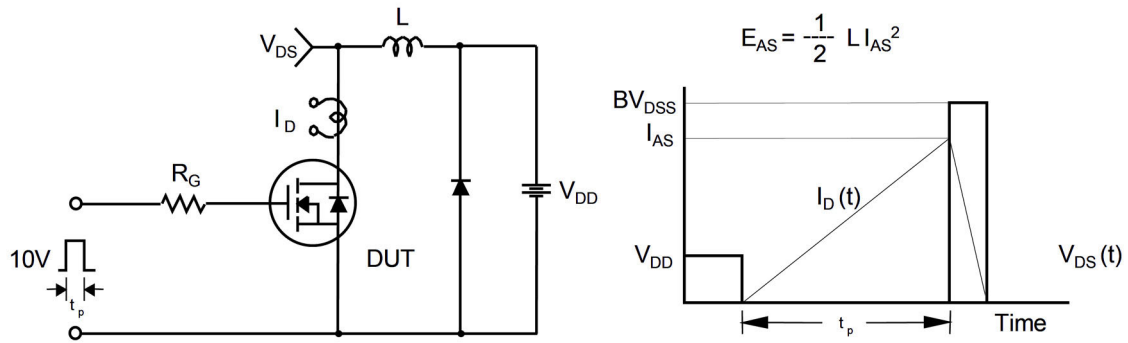


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

FDP045N10A / FDI045N10A

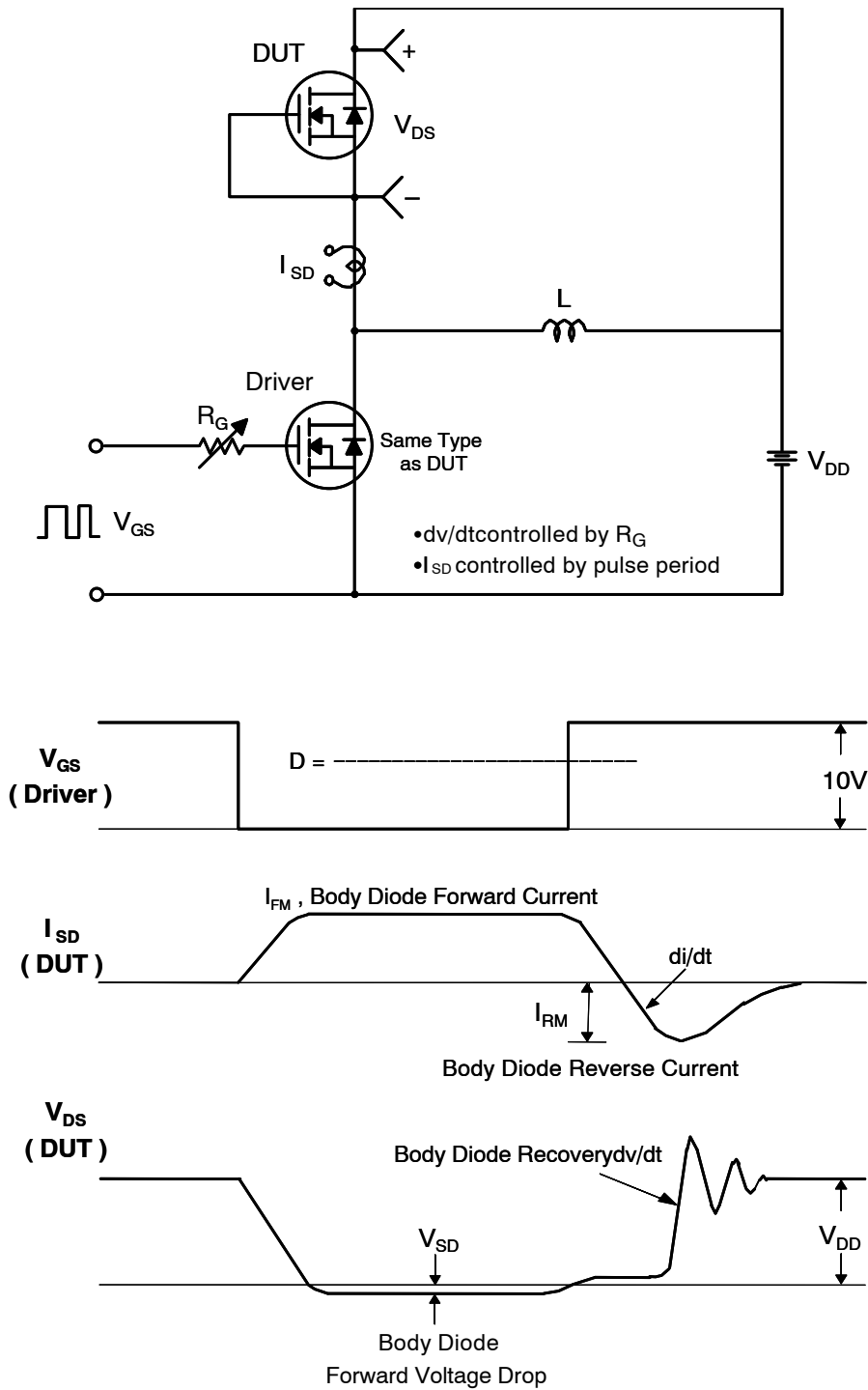
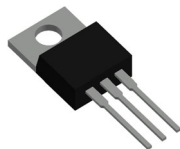


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

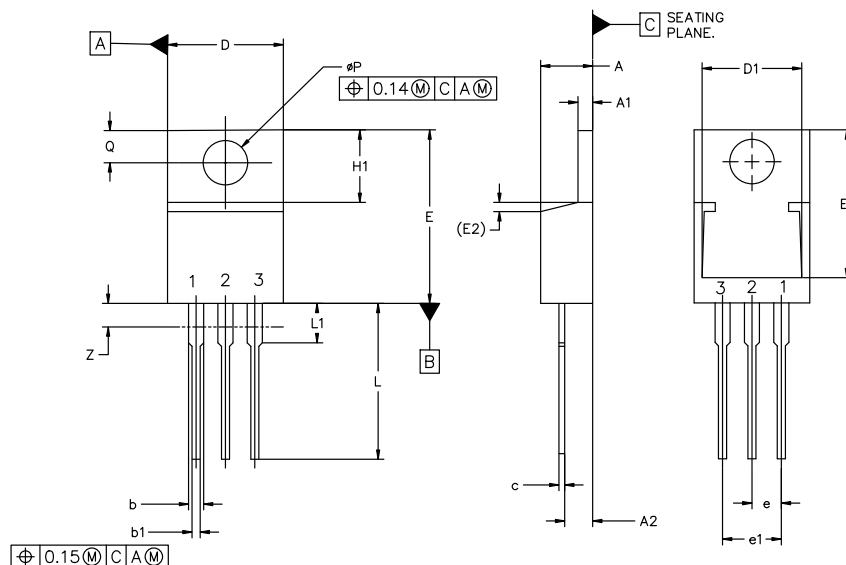


TO-220-3 10.10x15.12x4.45, 2.54P

CASE 221A

ISSUE AL

DATE 05 FEB 2025



MILLIMETERS			
DIM	MIN	NOM	MAX
A	4.07	4.45	4.83
A1	1.15	1.28	1.41
A2	2.04	2.42	2.79
b	1.15	1.34	1.52
b1	0.64	0.80	0.96
c	0.36	0.49	0.61
D	9.66	10.10	10.53
D1	8.43	8.63	8.83
E	14.48	15.12	15.75
E1	12.58	12.78	12.98
E2	1.27 REF		

MILLIMETERS			
DIM	MIN	NOM	MAX
e	2.42	2.54	2.66
e1	4.83	5.08	5.33
H1	5.97	6.22	6.47
L	12.70	13.49	14.27
L1	2.80	3.45	4.10
Q	2.54	2.79	3.04
øP	3.60	3.85	4.09
Z	---	---	3.48

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. BASE
2. EMITTER
3. COLLECTOR
4. EMITTER

STYLE 3:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 4:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. MAIN TERMINAL 2

STYLE 5:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 6:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

STYLE 8:
PIN 1. CATHODE
2. ANODE
3. EXTERNAL TRIP/DELAY
4. ANODE

STYLE 9:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

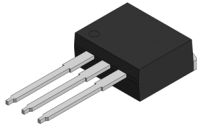
STYLE 10:
PIN 1. GATE
2. SOURCE
3. DRAIN
4. SOURCE

STYLE 11:
PIN 1. DRAIN
2. SOURCE
3. GATE
4. SOURCE

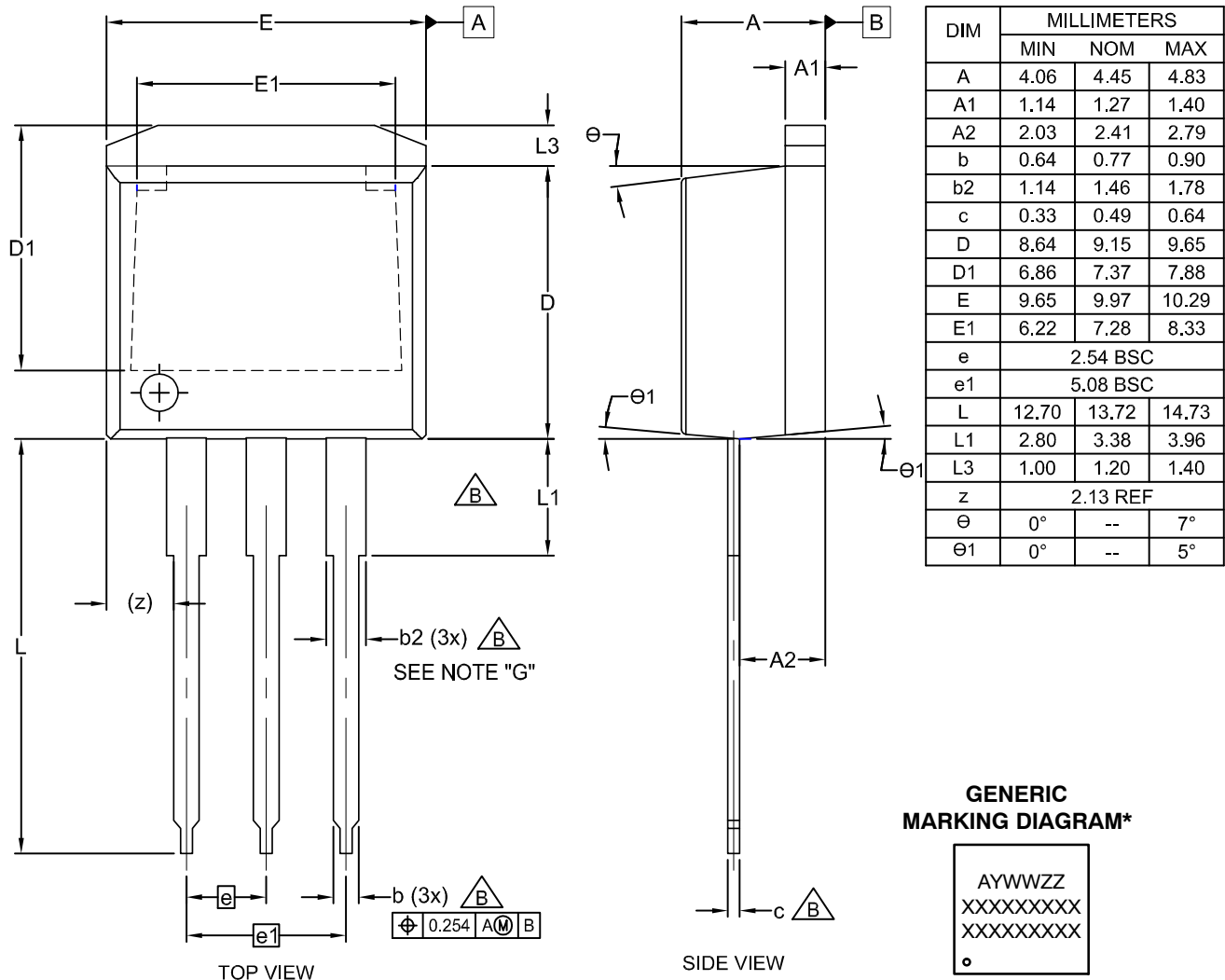
STYLE 12:
PIN 1. MAIN TERMINAL 1
2. MAIN TERMINAL 2
3. GATE
4. NOT CONNECTED

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DESCRIPTION:	TO-220-3 10.10x15.12x4.45, 2.54P	PAGE 1 OF 1

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I2PAK (TO-262 3 LD)
CASE 418AV
ISSUE A

DATE 30 AUG 2022



NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO T262 JEDEC VARIATION AA.
B. DOES NOT COMPLY JEDEC STD. VALUE.
C. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
E. DIMENSION AND TOLERANCE AS PER ANSI Y14.5-1994.
F. LOCATION OF PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF PACKAGE)
G. MAXIMUM WIDTH FOR F102 DEVICE = 1.35 MAX.

XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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